

Features

- CRM(CQ) Super_Junction technology
- Much lower Ron*A performance for On-state efficiency
- Much lower FOM for fast switching efficiency
- Integrated ESD protection diode

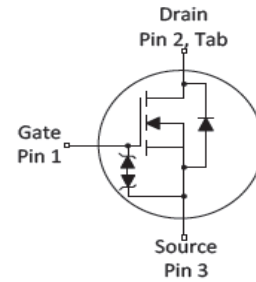
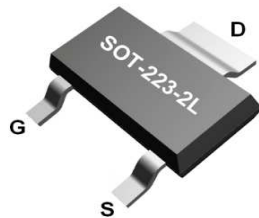
Applications

- LED/LCD/PDP TV and monitor Lighting
- Solar/Renewable/UPS-Micro Inverter System
- Charger
- Power Supply

Product Summary

VDS	700V
R _{DS(on)_typ}	1.15Ω
I _D	4A
ESD class(HMB)	2KV

100% Avalanche Tested


Package Marking and Ordering Information

Part #	Marking	Package	Packing	Reel Size	Tape Width	Qty
CRJB1K4N70G2E	-	SOT-223-2L	Tape&Reel	N/A	N/A	2500pcs

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V _{DS}	700	V
Continuous drain current	I _D	4	A
T _C = 25°C		2.6	
T _C = 100°C			
Pulsed drain current (T _C = 25°C, t _p limited by T _{jmax})	I _{D pulse}	17	A
Avalanche energy, single pulse (L=60mH, Rg=30Ω)	E _{AS}	50	mJ
Gate-Source voltage	V _{GS}	±30	V
Power dissipation (T _C = 25°C)	P _{tot}	5	W
Operating junction and storage temperature	T _j , T _{stg}	-55...+150	°C

Thermal Resistance

Parameter	Symbol	Value	Unit
Thermal resistance, junction – lead	R_{thJL}	25.30	°C/W
Thermal resistance, junction – ambient. Max	R_{thJA}	77	

Electrical Characteristic (at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		

Static Characteristic

Drain-source breakdown voltage	BV_{DSS}	700	-	-	V	$V_{GS}=0V, I_D=250\mu A$
Gate threshold voltage	$V_{GS(th)}$	3	3.5	4	V	$V_{DS}=V_{GS}, I_D=250\mu A$
Zero gate voltage drain current	I_{DSS}	-	-	1	μA	$V_{DS}=700V, V_{GS}=0V$ $T_C=25^\circ C$ $T_C=150^\circ C$
Gate-source leakage current	I_{GSS}	-	-	5	μA	$V_{GS}=\pm 30V, V_{DS}=0V$
Drain-source on-state resistance	$R_{DS(on)}$	-	1.15	1.40	Ω	$V_{GS}=10V, I_D=1.5A,$ $T_C=25^\circ C$ $T_C=150^\circ C$
Transconductance	g_{fs}	-	2.6	-	S	$V_{DS}=20V, I_D=1.5A$

Dynamic Characteristic

Input Capacitance	C_{iss}	-	255	-	μF	$V_{GS}=0V, V_{DS}=100V,$ $f=1MHz$
Output Capacitance	C_{oss}	-	11	-		
Reverse Transfer Capacitance	C_{rss}	-	5	-		
Gate Total Charge	Q_G	-	10.2	-	nC	$V_{GS}=10V, V_{DS}=480V,$ $I_D=1.5A, f=1MHz$
Gate-Source charge	Q_{gs}	-	2	-		
Gate-Drain charge	Q_{gd}	-	4.5	-		
Turn-on delay time	$t_{d(on)}$	-	11.6	-	ns	$T_j=25^\circ C, V_{GS}=10V,$ $I_D=1.5A, V_{DS}=400V, R_g=25\Omega$
Rise time	t_r	-	17	-		
Turn-off delay time	$t_{d(off)}$	-	47.7	-		
Fall time	t_f	-	90	-		
Gate resistance	R_G	-	7.9	-	Ω	$V_{GS}=0V, V_{DS}=0V, f=1MHz$

Body Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	V_{SD}	0.5	0.84	1	V	$V_{GS}=0V, I_{SD}=1.5A$
Body Diode Reverse Recovery Time	t_{rr}	-	133	-	ns	$I_{sd}=1.5A$ $dI/dt=100A/us, V_{ds}=100V$
Body Diode Reverse Recovery Charge	Q_{rr}	-	0.78	-	uC	

Typical Performance Characteristics

Fig 1. Output Characteristics (Tj=25°C)

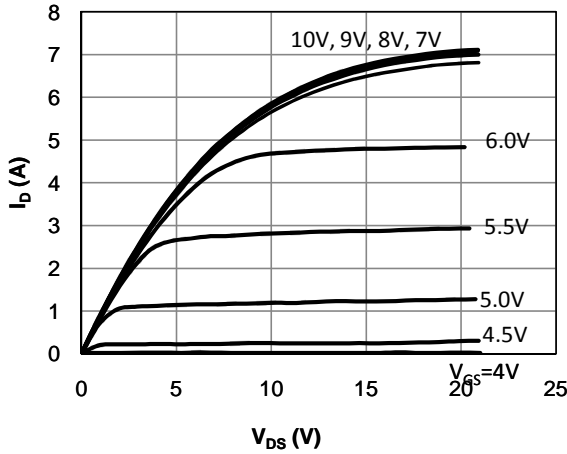


Fig 2. Output Characteristics (Tj=150°C)

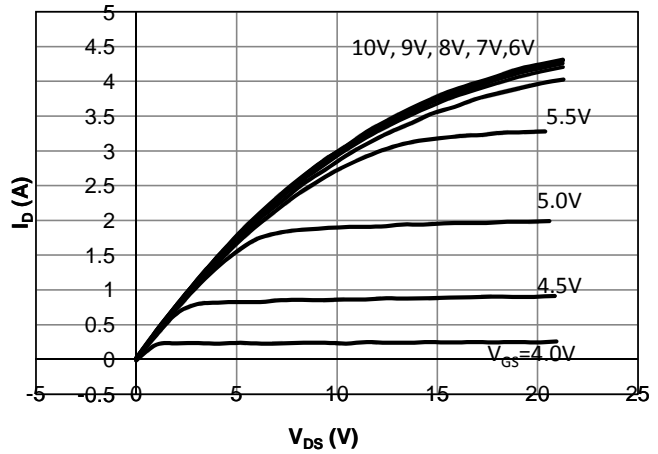


Fig 3: Transfer Characteristics

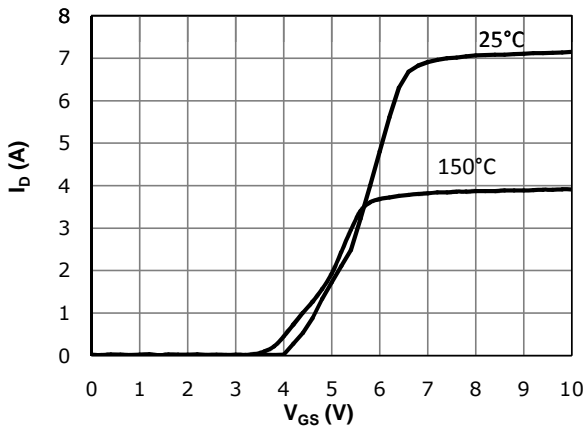


Fig 4: VTH Vs Tj Temperature Characteristics

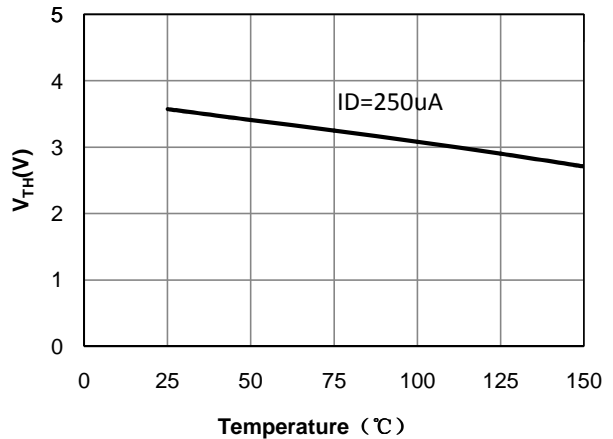


Fig 5: Rds(on) Vs Ids Characteristics(Tc=25°C)

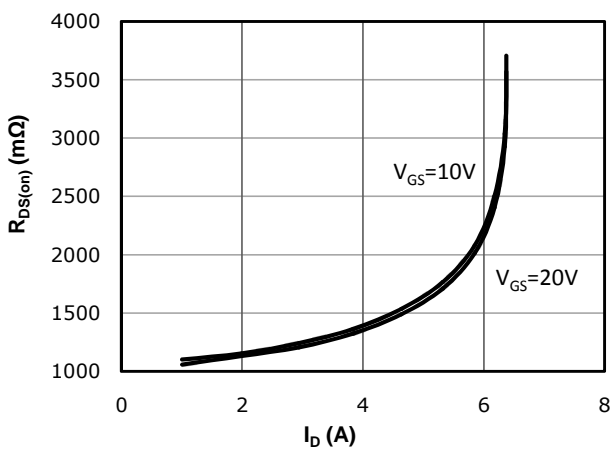


Fig 6: Rds(on) vs. Temperature

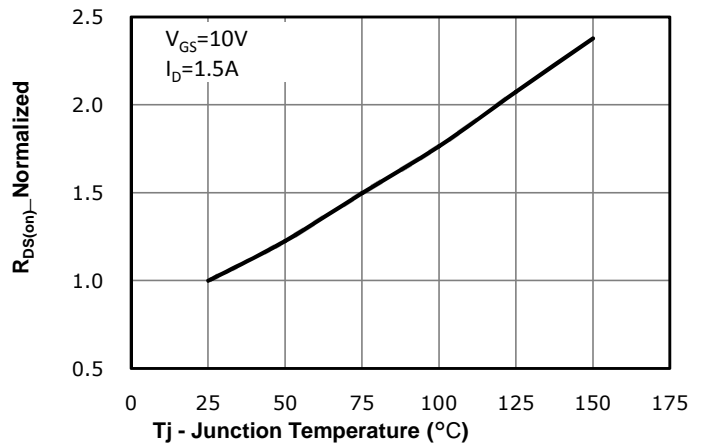


Fig 7: BVdss vs. Temperature

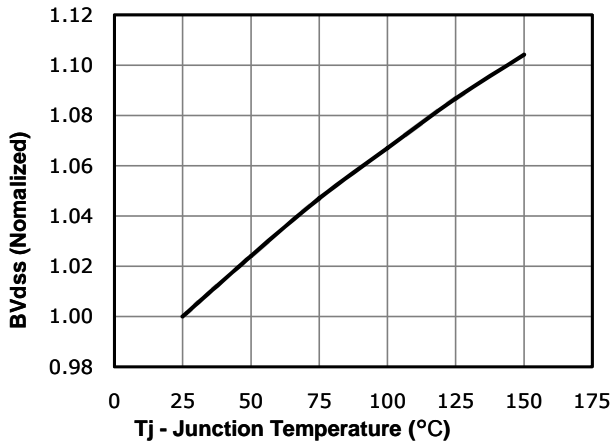


Fig 8: Rds(on) vs. Gate Voltage

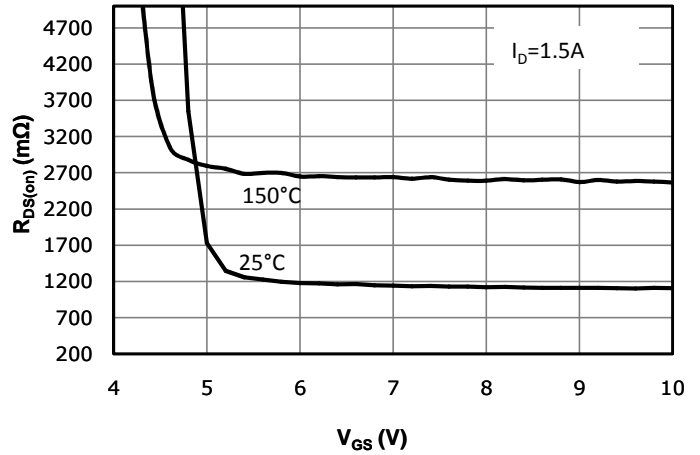


Fig 9: Body-diode Forward Characteristics

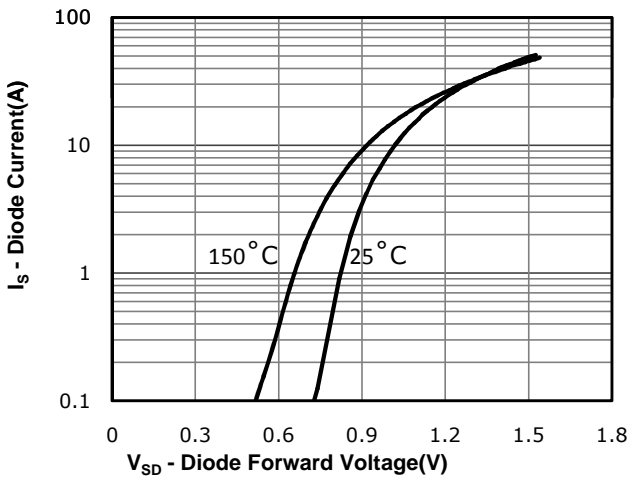


Fig 10: Gate Charge Characteristics

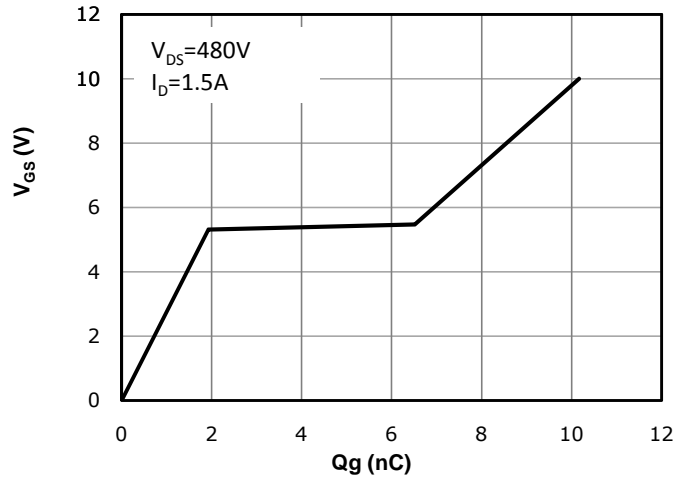


Fig 11: Capacitance Characteristics

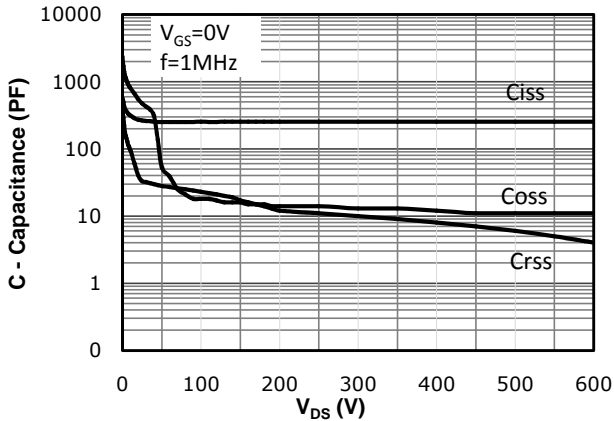


Fig 12: Safe Operating Area

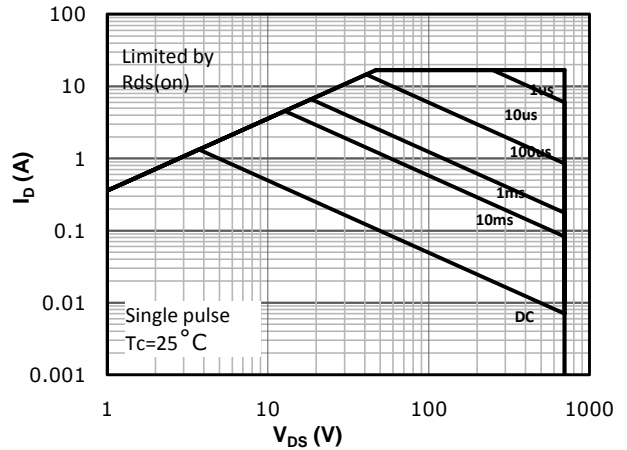
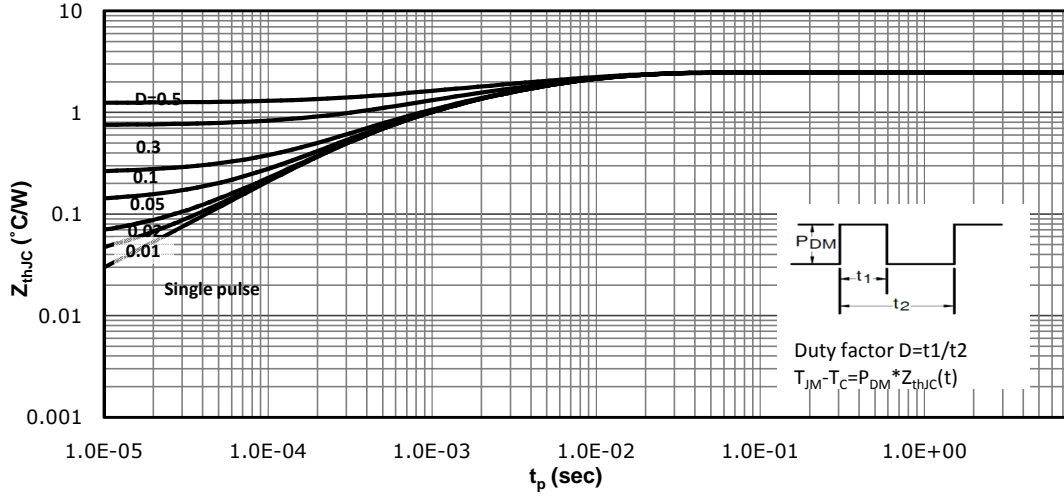
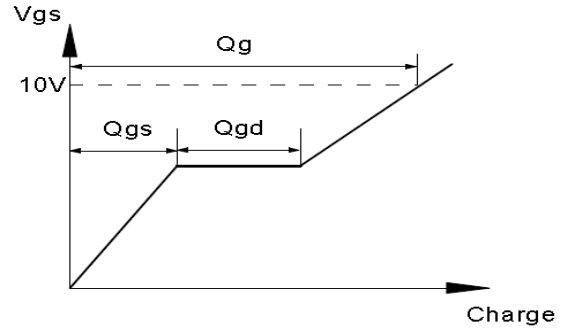
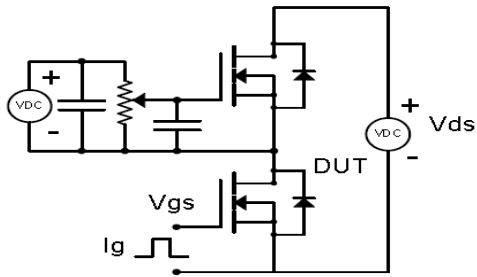


Fig 13: Max. Transient Thermal Impedance

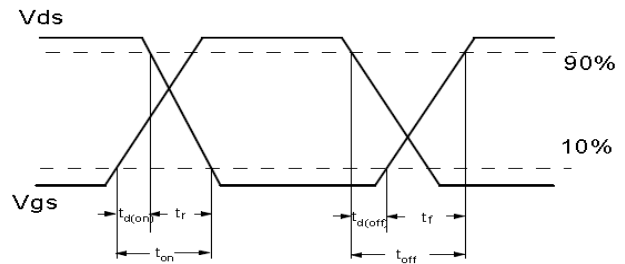
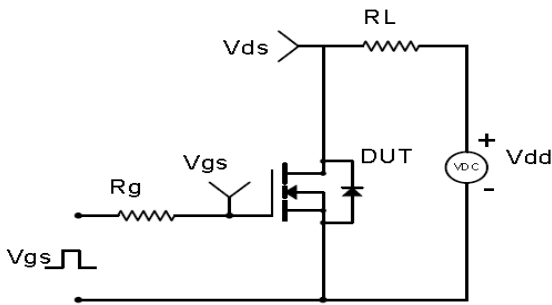


Test Circuit & Waveform

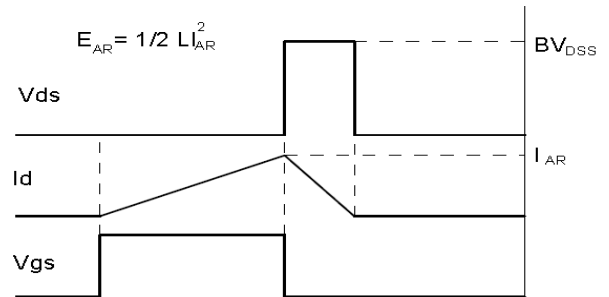
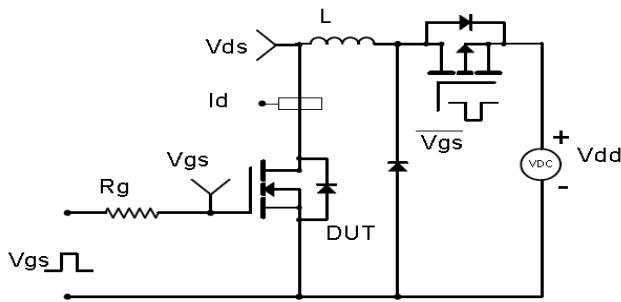
Gate Charge Test Circuit & Waveform



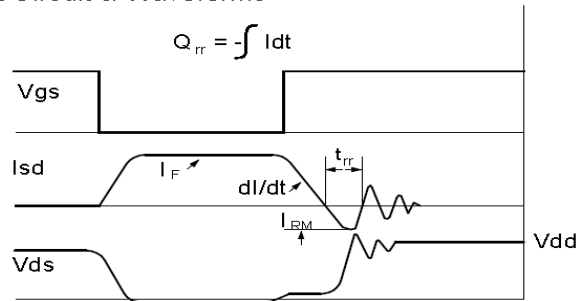
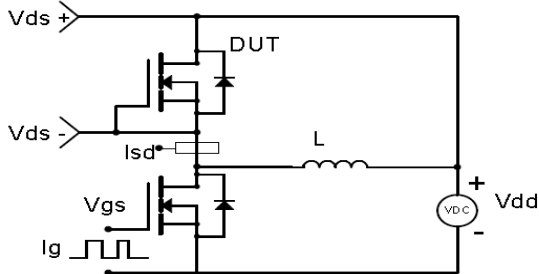
Resistive Switching Test Circuit & Waveforms



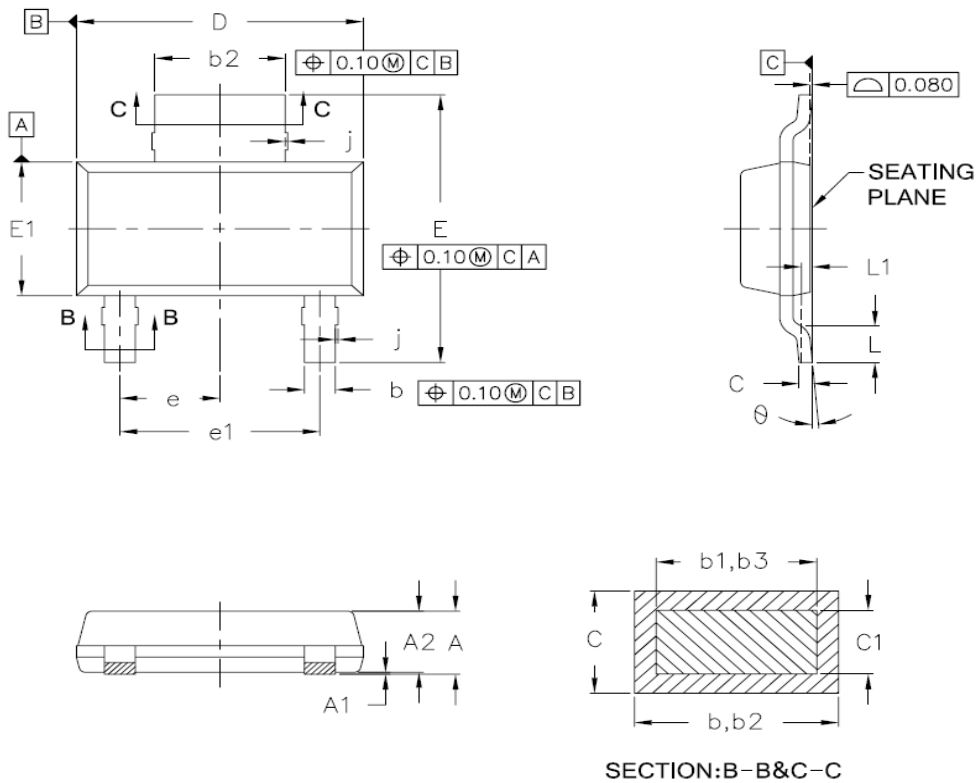
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Package Outline: SOT-223-2L



SYMBOLS	COMMON			
	MM		INCH	
	MIN.	MAX.	MIN.	MAX.
A	—	1.80	—	0.071
A1	0.02	0.10	0.001	0.004
A2	1.50	1.70	0.059	0.067
b	0.66	0.84	0.026	0.033
b1	0.60	0.79	0.024	0.031
b2	2.90	3.10	0.114	0.122
b3	2.84	3.05	0.112	0.120
c	0.23	0.35	0.009	0.014
c1	0.23	0.33	0.009	0.013
D	6.30	6.70	0.248	0.264
E	6.70	7.30	0.264	0.287
E1	3.30	3.70	0.130	0.146
e	2.30 BSC.		0.091 BSC.	
e1	4.60 BSC.		0.182 BSC.	
L	0.81	—	0.032	—
L1	0.25 BSC.		0.010 BSC.	
θ	0°	10°	0°	10°
j	—	0.13	—	0.005

Revision History

Revision	Date	Major changes
1.0	2020-6-30	Release of first version

Disclaimer

Unless otherwise specified in the datasheet, the product is designed and qualified as a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability, such as automotive, aviation/aerospace and life-support devices or systems.

Any and all semiconductor products have certain probability to fail or malfunction, which may result in personal injury, death or property damage. Customer are solely responsible for providing adequate safe measures when design their systems.

CRM(CQ) reserves the right to improve product design, function and reliability without notice.

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[>>CRMICRO\(华润微\)](#)